DCS1800/1900 POWER AMPLIFIER

Typical Applications

- 4.8 V DCS1800/1900 Handsets
- 3V DECT Handsets and Base Stations
- Commercial and Consumer Systems
- Portable Battery Powered Equipment

Product Description

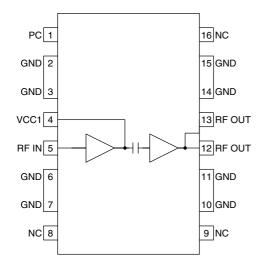
The RF2145 is a high power, high efficiency amplifier IC. The device is manufactured on an advanced Gallium Arsenide Heterojunction Bipolar Transistor (HBT) process, and has been designed for use as the final RF amplifier in a 4-cell DCS1800 or DCS1900 handset. The device is packaged in a 16-lead plastic package with wide ground leads, and is self-contained with the exception of the output matching network and power supply feed line. Only a single positive voltage is required to operate with full power and efficiency, and on-board power control and power-down functions are provided.

Package Style: SOP-16 QBW1

Optimum Technology Matching® Applied

☐ Si BJT ☑ GaAs HBT ☐ Si Bi-CMOS ☐ SiGe HBT ☐

☐ GaAs MESFET☐ Si CMOS



Functional Block Diagram

Features

- Single 4.8V Power Supply
- +32dBm Output Power
- 28dB Small Signal Gain
- 55% Power Added Efficiency
- Power Control
- 1700 MHz to 1900 MHz Frequency Range

Ordering Information

RF2145 DCS1800/1900 Power Amplifier RF2145 PCBA Fully Assembled Evaluation Board

RF Micro Devices, Inc. 7625 Thorndike Road Greensboro, NC 27409, USA Tel (336) 664 1233 Fax (336) 664 0454 http://www.rfmd.com

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RF2145

Absolute Maximum Ratings

Parameter	Rating	Unit
Supply Voltage	-0.5 to +7.5	V_{DC}
Power Control Voltage (V _{PC})	-0.5 to +3.0	V
DC Supply Current	675	mA
Input RF Power	+12	dBm
Output Load VSWR	5:1	
Ambient Operating Temperature	-40 to +85	°C
Storage Temperature	-40 to +150	$^{\circ}$



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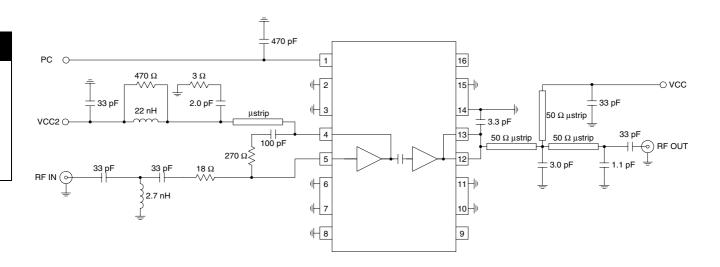
Parameter	Specification		Unit	Condition		
Parameter	Min.	Min. Typ.		Ollit	Condition	
Overall					T=25 °C, V _{CC} =4.8 V, V _{PC} =2.5 V,	
Overall					P _{IN} =+8dBm, Freq=1750MHz	
Operating Frequency Range		1710 to 1785 1850 to 1910		MHz		
Usable Frequency Range		1700 to 1990		MHz		
Maximum Output Power		+32		dBm	1/8 Duty cycle with 600 µs pulse width	
Total Efficiency		55		%	At maximum output power	
Input Power for Max Output		+8		dBm		
Input Intermodulation Distortion		-57		dBc	Input signal consists of F ₁ at 1785MHz at +8dBm, F ₂ at 1765MHz at -42dBm. Output power at F ₁ is set to +32.5dBm. Specified power level at 1805MHz relative to F ₁ . This refers to the amount of TX band noise which converts into the receive band.	
		-48		dBc	Input signal consists of F ₁ at 1785MHz at +8dBm, F ₂ at 1765MHz at -32dBm. Output power at F ₁ is set to +32.5dBm. Specified power level at 1805MHz relative to F ₁ . This refers to the amount of TX band noise which converts into the receive band.	
Output Noise Power in Receive Band		-137		dBm/Hz	Any gain setting	
Isolation		-25		dBm	In "OFF" state, P _{IN} =+8dBm	
Second Harmonic		-48		dBc	The state of the s	
Third Harmonic		<-60		dBc		
Input Impedance		50		Ω		
Input VSWR			3.8:1		Worst-case across the band. Using evaluation board; can be different with other layouts	
Output Load VSWR	3:1				Spurious<-60dBc	
Power Control						
Power Control "ON"		2.5	3.0	V	Threshold voltage	
Power Control "OFF"	0.2	0.5		V	Threshold voltage	
Current into PC Input		15		mA	In "ON" state	
			10	μΑ	In "OFF" state	
Power Control Range	45			dB		
Turn On/Off TIme			100	ns		
Power Supply						
Power Supply Voltage		4.8		V	Specifications	
	2.7		6.5	V	Operating limits	
Power Supply Current		550		mA	DC Current at maximum output power	
			10	μΑ	V _{PC} =0.5 V	

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Pin	Function	Description	Interface Schematic
1	PC	Power control pin. This also provides power down when V_{PC} is less than +0.5V. Full power is achieved at 2.5V, and >45dB of gain control is obtainable over the full range. Approximately 15mA current is drawn into this pin at full power.	PC O To RF Stages
2	GND	Ground connection. This pin should be connected to the ground plane through a short path and may be combined with the ground plane from Pins 3, 6, 7, 10, 11, 14, and 15. All four of these wide leads are tied together internally to provide a low-inductance and low thermal resistance path to external ground. Ground vias should be placed as close as possible to each ground lead.	
3	GND	Same as pin 2.	
4	VCC1	Power supply pin for the first stage. Also provides tuning for interstage match.	VCC1 RF IN O From Bias Stages
5	RF IN	RF input. This input is DC coupled, so an external blocking capacitor is required if this pin is connected to a DC path.	See pin 4 schematic.
6	GND	Same as pin 2.	
7	GND	Same as pin 2.	
8	NC	No connection.	
9	NC	No connection.	
10	GND	Same as pin 2.	
11	GND	Same as pin 2.	
12	RF OUT	RF output pin. Bias is also fed to the final stage through this wide lead. External matching is most easily achieved with a series transmission line and shunt capacitors, as shown in the application schematic.	RF OUT From Bias Stages
13	RF OUT	Same as pin 12.	
14	GND	Same as pin 2.	
15	GND	Same as pin 2.	
16	NC	No connection.	

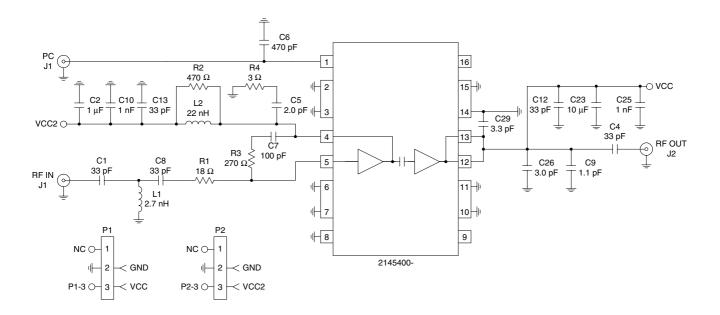
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Application Schematic DCS 1800



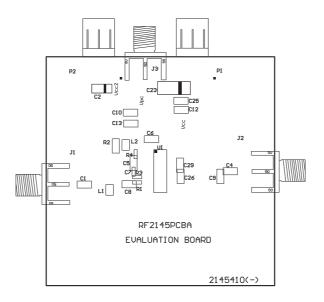
Evaluation Board Schematic

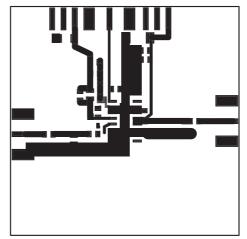
(Download Bill of Materials from www.rfmd.com.)



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Evaluation Board Layout 2" x 2"





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